

2-line IPAD™, EMI filter and ESD protection

Datasheet - production data

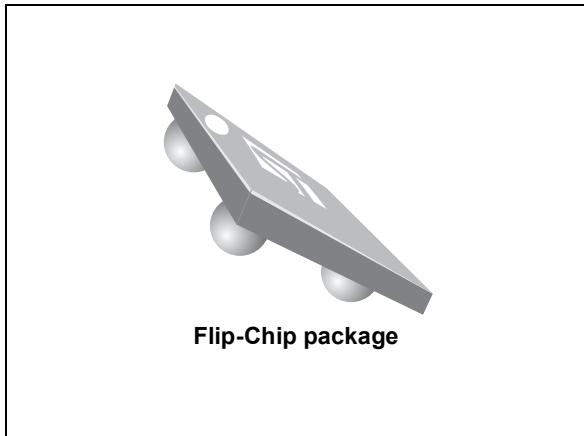
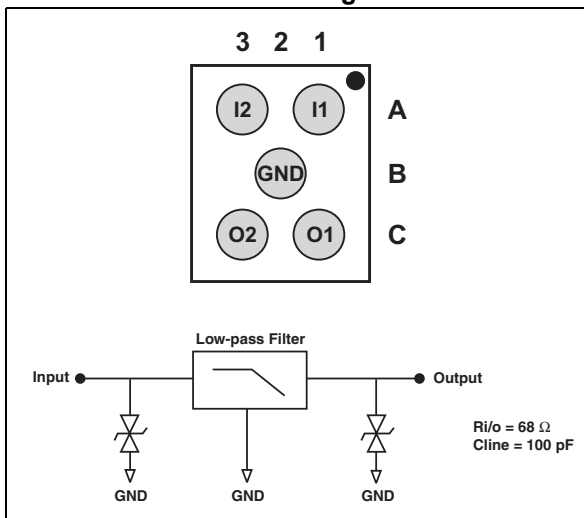


Figure 1. Pin configuration (bump side) and basic cell configuration



- High reliability offered by monolithic integration
- High reducing of parasitic elements through integration and wafer level packaging

Complies with the following standards:

- IEC 61000-4-2 level 4, on input pins
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- IEC 61000-4-2 Level 1, on output pins
 - 2 kV (air discharge)
 - 2 kV (contact discharge)
- MIL STD 883E - Method 3015-6 Class 3

Application

- Mobile phones (differential microphone filtering and ESD protection).

Description

The EMIF02-MIC03F2 is a highly integrated device designed to suppress EMI/RFI noise in all systems subjected to electromagnetic interferences. The EMIF02 Flip-Chip packaging means the package size is equal to the die size.

This filter includes an ESD protection circuitry which prevents damage to the application when subjected to ESD surges up 15 kV.

Features

- EMI symmetrical (I/O) low-pass filter
- High efficiency in EMI filtering
- Very low PCB space consuming:
1.07 mm x 1.47 mm
- Very thin package: 0.65 mm
- High efficiency in ESD suppression

TM: IPAD is a trademark of STMicroelectronics.

1 Electrical characteristics

Table 1. Absolute maximum ratings (T_{AMB} = 25 °C)

Symbol	Parameter	Value	Unit
T _j	Maximum junction temperature	125	°C
Top	Operating temperature range	-40 to +85	°C
Tstg	Storage temperature range	-55 to +150	°C

Table 2. Electrical characteristics (T_{amb} = 25 °C)

Symbol	Parameters
V _{BR}	Breakdown voltage
I _{RM}	Leakage current @ V _{RM}
V _{RM}	Stand-off voltage
V _{CL}	Clamping voltage
R _d	Dynamic impedance
I _{PP}	Peak pulse current
R _{I/O}	Series resistance between Input & Output
C _{line}	Input capacitance per line

Table 3.

Symbol	Test condition	Min	Typ	Max	Unit
V _{BR}	I _R = 1 mA	6	8		V
I _{RM}	V _{RM} = 3 V per line			500	nA
R _{I/O}	Tolerance ± 20%		68		Ω
C _{line}	V _R = 0 V		100		pF

Figure 2. Attenuation simulation with 1 kΩ input and 10 kΩ output

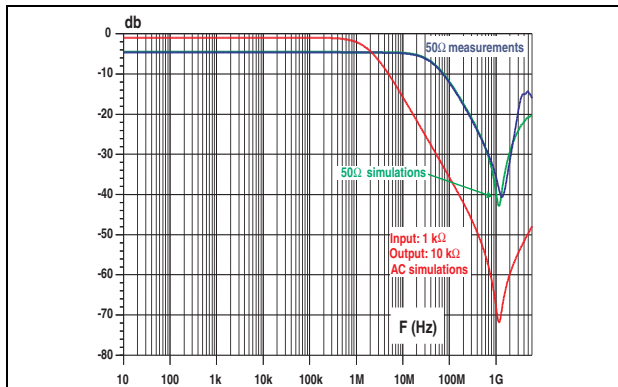


Figure 3. Analog crosstalk measurements

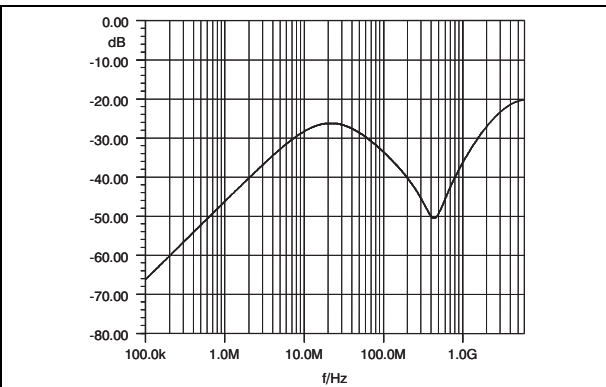


Figure 4. ESD response to IEC61000-4-2 (+15kV air discharge) on one input V(in) and one output V(out)

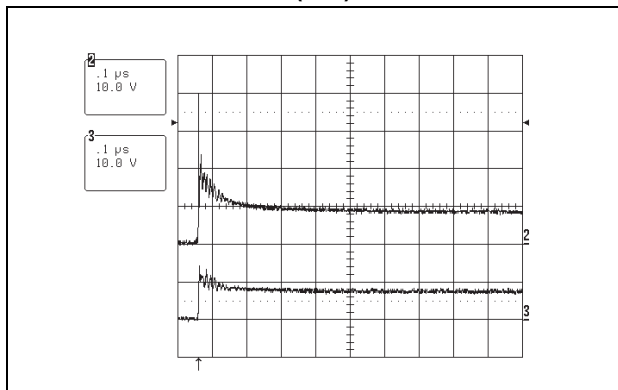


Figure 5. ESD response to IEC61000-4-2 (-15kV air discharge) on one input V(in) and one output V(out)

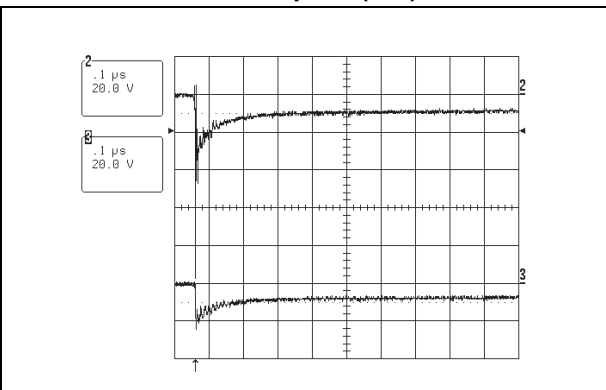


Figure 6. Line capacitance versus applied voltage.

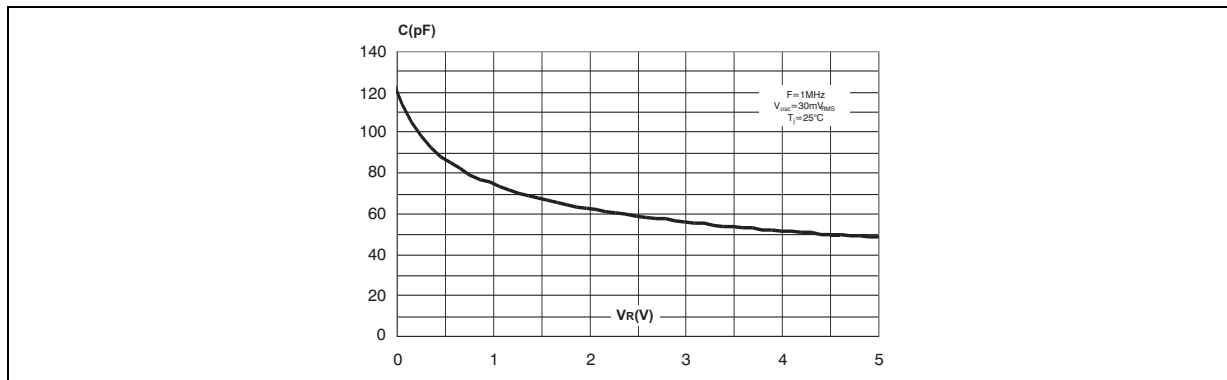


Figure 7. Aplac mode

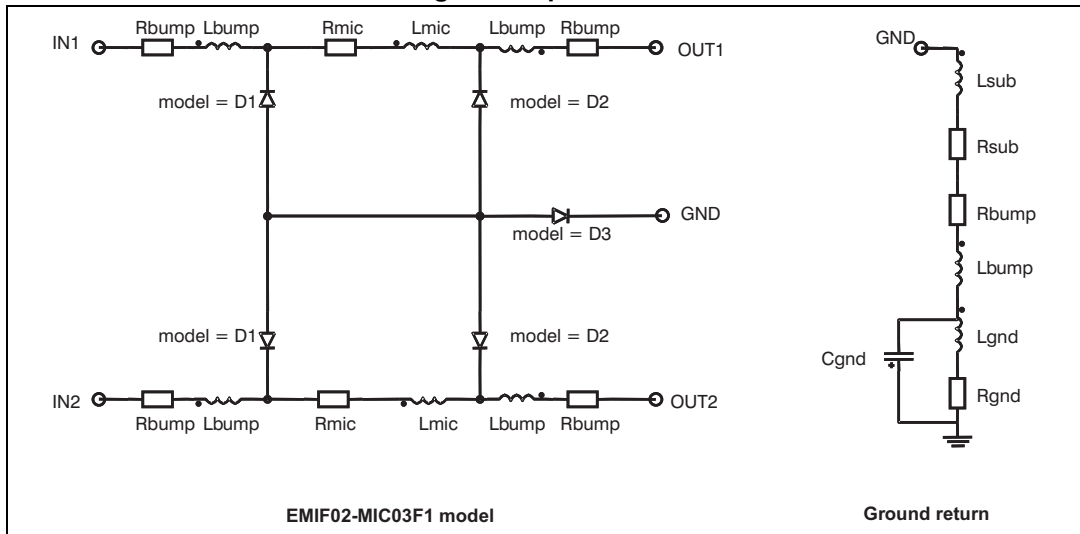
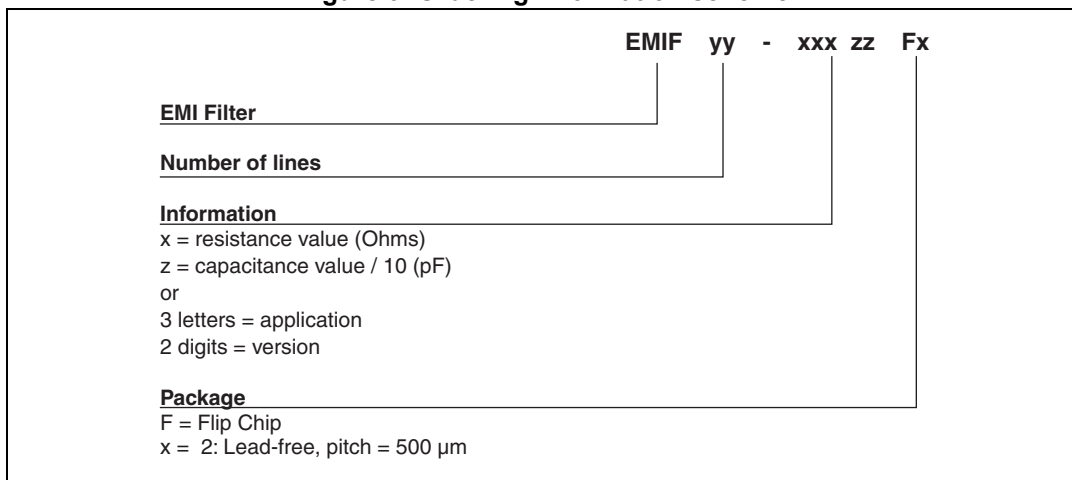


Figure 8. Aplac parameters

Model D1	Model D3	Model D2	aplacvar Rmic 68
CJO=Cdiode1	CJO=Cdiode3	CJO=Cdiode2	aplacvar Lmic 10p
BV=7	BV=7	BV=7	aplacvar Cdiode1 100pF
IBV=1u	IBV=1u	IBV=1u	aplacvar Cdiode2 3.6pF
IKF=1000	IKF=1000	IKF=1000	aplacvar Cdiode3
IS=10f	IS=10f	IS=10f	1.17nF
ISR=100p	ISR=100p	ISR=100p	aplacvar Lbump 50pH
N=1	N=1	N=1	aplacvar Rbump 20m
M=0.3333	M=0.3333	M=0.3333	aplacvar Rsub 0.5m
RS=0.7	RS=0.12	RS=0.3	aplacvar Rgnd 10m
VJ=0.6	VJ=0.6	VJ=0.6	aplacvar Lgnd 50pH
TT=50n	TT=50n	TT=50n	aplacvar Cgnd 0.15pF
			aplacvar Lsub 10pH

2 Ordering information scheme

Figure 9. Ordering information scheme



3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 10. Flip Chip dimensions

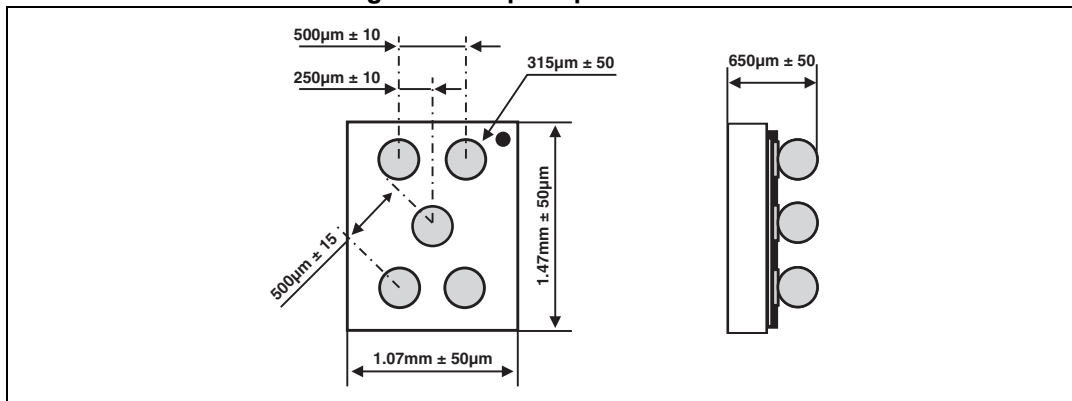


Figure 11. Footprint

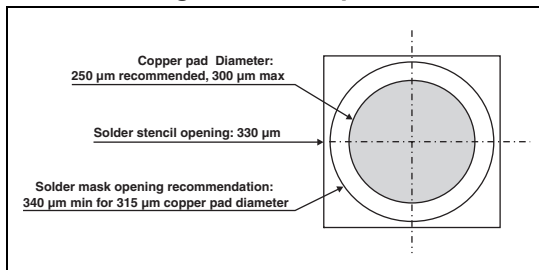


Figure 12. Marking

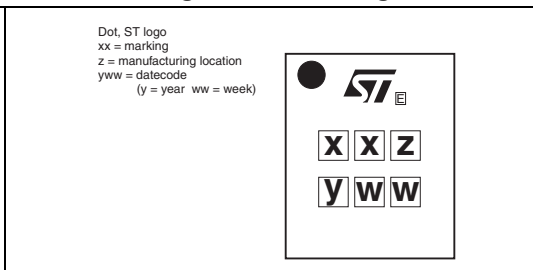
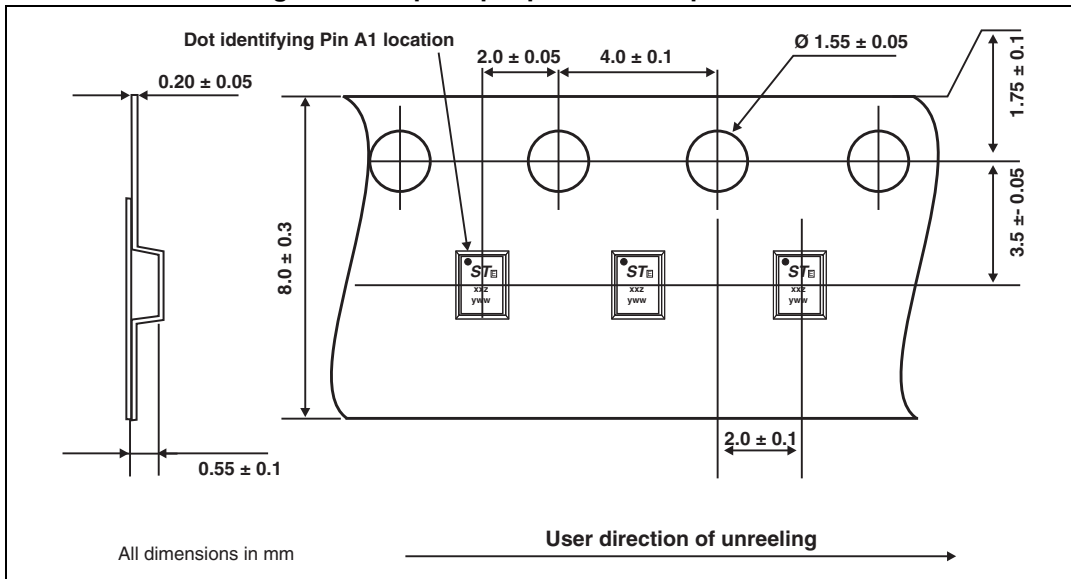


Figure 13. Flip Chip tape and reel specification



4 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF02-MIC03F2	FW	Flip Chip	2.1 mg	5000	Tape and reel (7")

Note: More packing information is available in the applications note:
 AN1235: "Flip Chip: package description and recommendations for use"
 AN 1751: "EMI filters: Recommendations and measurements"

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
14-Oct-2006	1	Initial release
31-Mar-2014	2	Reformatted to current standards. Added ECOPACK statement. Updated Figure 2 and Figure 13 .
18/07/2014	3	Updated typo error on Features .

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2014 STMicroelectronics – All rights reserved



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.